

What is claimed is:

1. Circuit board with at least one rigid area (2) and at least one flexible area (3), with a rigid individual layer (4) which is provided with printed conductors or is copper-clad on one or both sides, with an adhesive medium (7) and with at least one copper foil (8), the adhesive medium (7) having recesses in the flexible area (3), characterized in that at least in the rigid area (2) there is no flexible individual layer (9) between the adhesive medium (7) and the copper foil (8).
2. Circuit board as claimed in claim 1, wherein in the flexible area (3) there is no flexible individual layer (9) between the rigid individual layer (4) and the copper foil (8) either.
3. Circuit board as claimed in claim 1, wherein in the flexible area (3) on the inner side of the copper foil (8) an insulating layer (11) is applied directly to the copper foil (8).
4. Circuit board as claimed in one of claims 1 to 3, wherein at least in the flexible area (3) another insulating layer (12) is applied to the outer side of the copper foil (8).
5. Circuit board as claimed in one of claims 1 to 4, wherein the insulating layer (11) and/or another insulating layer (12) is a resist, especially a flexible solder resist, which has been applied to the copper foil (8).
6. Multi-layer circuit board with at least one rigid and at least one flexible area, consisting of at least one circuit board as claimed in one of claims 1 to 5, wherein there are several rigid individual layers which are provided with printed conductors or which are copper-clad on one or both sides, and/or several copper foils which are provided with an insulating layer in the flexible area, and wherein the rigid individual layers are cemented among one another and/or the copper foils are cemented among one another and/or the rigid

individual layers and the copper foils are cemented to one another by means of adhesive media.

7. Process for producing rigid-flexible circuit boards with at least one rigid individual layer which is provided with printed conductors or is copper-clad on one or both sides, with an adhesive medium and with at least one copper foil, the adhesive medium having recesses in the flexible area,

wherein first an uncured insulating layer is applied to one side of the copper foil in the flexible area,

wherein the insulating layer is cured to such an extent that the free surface loses its adhesive capacity,

wherein the copper foil which has been pretreated in this way is cemented by means of the adhesive medium to the rigid individual layer and

wherein then in the flexible area of the circuit board a piece is removed from the rigid individual layer.

8. Process for producing rigid-flexible circuit boards with at least one rigid individual layer which is provided with printed conductors or is copper-clad on one or both sides, with an adhesive medium and with at least one copper foil, the adhesive medium having recesses in the flexible area,

wherein the copper foil is cemented to the rigid individual layer by means of an adhesive medium,

wherein then in the flexible area of the circuit board a piece is removed from the rigid individual layer and

wherein then an uncured insulating layer is applied to the inner side of the copper foil in the flexible area.

9. Process as claimed in claim 7 or 8, wherein at least in the flexible area of the circuit board another insulating layer is applied to the outer side of the copper foil.

10. Process as claimed in one of claims 7 to 9, wherein the insulating layer or insulating layers is or are sprayed, rolled or printed onto the copper foil.